RB751 series

Schottky barrier single diodes

Rev. 01 — 21 May 2007 Product data sheet

1. Product profile

1.1 General description

Planar Schottky barrier single diodes with an integrated guard ring for stress protection, encapsulated in small Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package		Package configuration
	NXP	JEITA	
RB751CS40	SOD882	-	leadless ultra small
RB751S40	SOD523	SC-79	ultra small
RB751V40	SOD323	SC-76	very small

1.2 Features

- Low forward voltage
- Low capacitance

1.3 Applications

- Ultra high-speed switching
- Voltage clamping
- Line termination
- Reverse polarity protection

1.4 Quick reference data

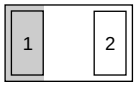
Table 2. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_F	forward current			-	-	120	mA
V_{RRM}	repetitive peak reverse voltage			-	-	40	V
V_F	forward voltage	I_F = 1 mA	[1]	-	-	370	mV

[1] Pulse test: $t_p \leq 300\ \mu s$; $\delta \leq 0.02$.

2. Pinning information

Table 3. Pinning

Pin	Description		Simplified outline	Symbol
SOD882				
1	cathode	[1]	 Transparent top view	 sym001
2	anode			
SOD323; SOD523				
1	cathode	[1]	 001aab540	 sym001
2	anode			

[1] The marking bar indicates the cathode.

3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
RB751CS40	-	leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.5 mm	SOD882
RB751S40	SC-79	plastic surface-mounted package; 2 leads	SOD523
RB751V40	SC-76	plastic surface-mounted package; 2 leads	SOD323

4. Marking

Table 5. Marking codes

Type number	Marking code
RB751CS40	F6
RB751S40	G4
RB751V40	W8

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage			-	40	V
V_R	reverse voltage			-	40	V
I_F	forward current			-	120	mA
I_{FSM}	non-repetitive peak forward current	square wave; $t_p < 10$ ms		-	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]			
	RB751CS40		[2]	-	250	mW
	RB751S40		[2]	-	280	mW
	RB751V40			-	280	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			–65	+150	°C
T_{stg}	storage temperature			–65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]				
	RB751CS40		[2]	-	-	500	K/W
	RB751S40		[2]	-	-	450	K/W
	RB751V40			-	-	450	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

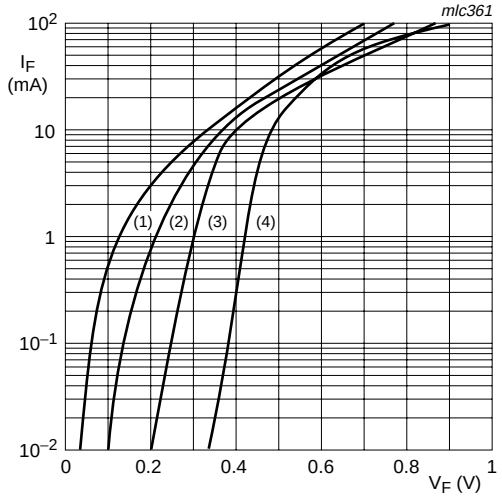
7. Characteristics

Table 8. Characteristics

T_{amb} = 25 °C unless otherwise specified.

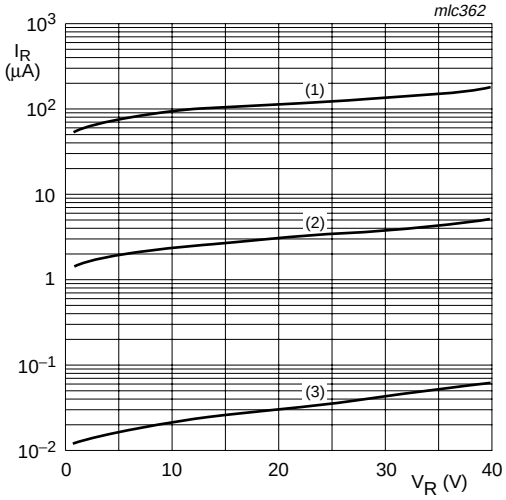
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_F	forward voltage	I_F = 1 mA	[1]	-	-	370	mV
I_R	reverse current	V_R = 30 V		-	-	0.5	µA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz		-	2	-	pF

[1] Pulse test: $t_p \leq 300$ µs; $\delta \leq 0.02$.



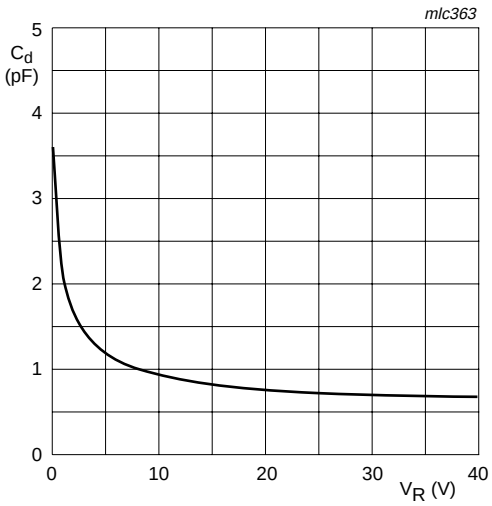
(1) T_{amb} = 125 °C
(2) T_{amb} = 85 °C
(3) T_{amb} = 25 °C
(4) T_{amb} = −40 °C

Fig 1. Forward current as a function of forward voltage; typical values



(1) T_{amb} = 125 °C
(2) T_{amb} = 85 °C
(3) T_{amb} = 25 °C

Fig 2. Reverse current as a function of reverse voltage; typical values



f = 1 MHz; T_{amb} = 25 °C

Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Package outline

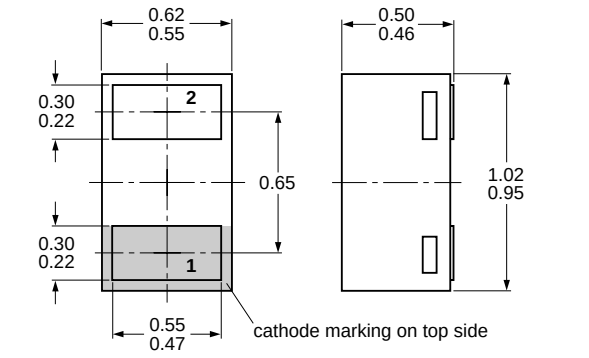


Fig 4. Package outline SOD882

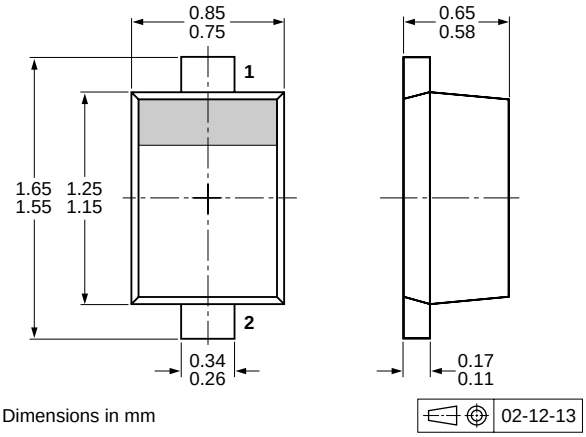


Fig 5. Package outline SOD523 (SC-79)

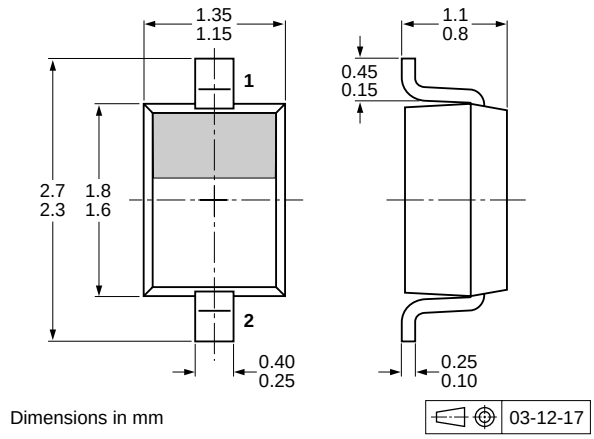


Fig 6. Package outline SOD323 (SC-76)

9. Packing information

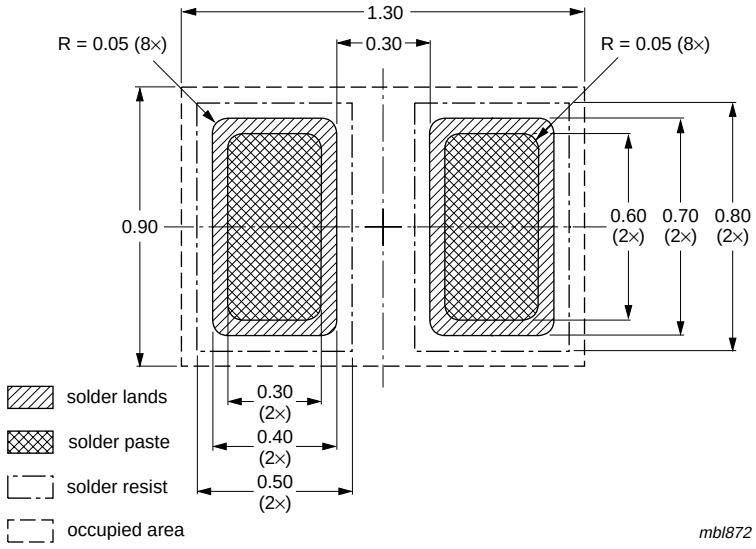
Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description	Packing quantity		
			3000	8000	10000
RB751CS40	SOD882	2 mm pitch, 8 mm tape and reel	-	-	-315
RB751S40	SOD523	2 mm pitch, 8 mm tape and reel	-	-315	-
		4 mm pitch, 8 mm tape and reel	-115	-	-135
RB751V40	SOD323	4 mm pitch, 8 mm tape and reel	-115	-	-135

[1] For further information and the availability of packing methods, see Section 13.

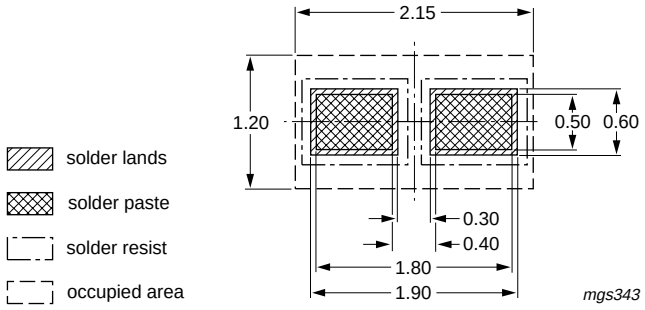
10. Soldering



Reflow soldering is the only recommended soldering method.

Dimensions in mm

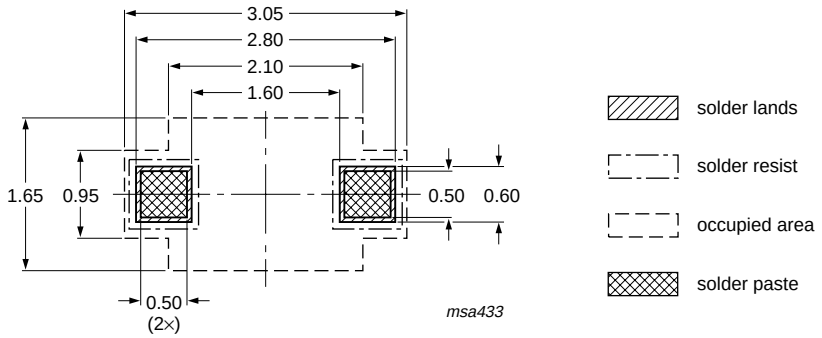
Fig 7. Reflow soldering footprint SOD882



Reflow soldering is the only recommended soldering method.

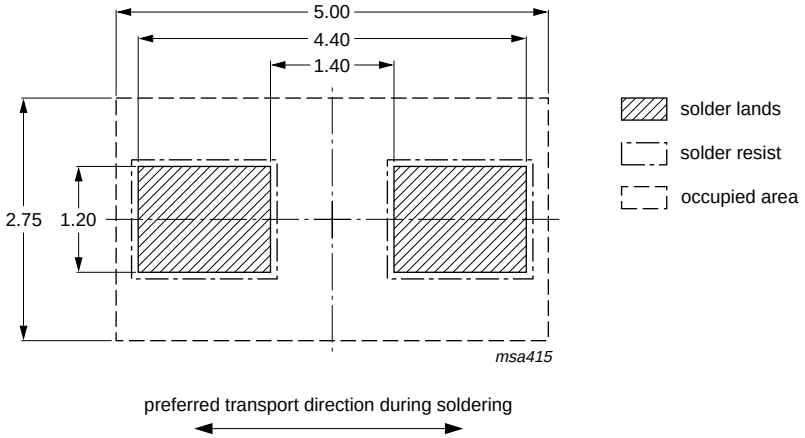
Dimensions in mm

Fig 8. Reflow soldering footprint SOD523 (SC-79)



Dimensions in mm

Fig 9. Reflow soldering footprint SOD323 (SC-76)



Dimensions in mm

Fig 10. Wave soldering footprint SOD323 (SC-76)

11. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
RB751_SER_1	20070521	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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14. Contents

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